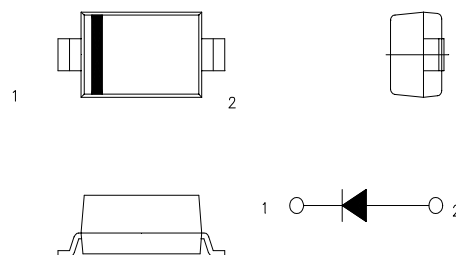


# SBD Type : EP05Q03L

## FEATURES

- \* EDEC SOD-123 Package
- \* Very Low profile 1.1mm Max
- \* Extremely Low Forward Voltage Drop
- \* Low Power Loss,High Efficiency
- \* High Surge Capability
- \* Low Thermal Resistance
- \* Packaged in 8mm Tape and Reel

## OUTLINE DRAWING



## Maximum Ratings

Approx Net Weight:0.011g

Rating	Symbol	EP05Q03L		Unit
Repetitive Peak Reverse Voltage	$V_{RRM}$	30		V
Average Rectified Output Current	$I_O$	0.49	$T_a=25^{\circ}\text{C}$ * 1 50Hz Half Sine Wave,	A
		0.50	$T_l=106^{\circ}\text{C}$ Resistive Load	
RMS Forward Current	$I_{F(RMS)}$	0.785		A
Surge Forward Current	$I_{FSM}$	8	50Hz Half Sine Wave,1cycle Non-repetitive	A
Operating JunctionTemperature Range	$T_{jw}$	-40 to +150		$^{\circ}\text{C}$
Storage Temperature Range	$T_{stg}$	-40 to +150		$^{\circ}\text{C}$

## Electrical • Thermal Characteristics

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current	$I_{RM}$	$T_j= 25^{\circ}\text{C}$ , $V_{RM}= V_{RRM}$	-	-	200	$\mu\text{A}$
Peak Forward Voltage	$V_{FM}$	$T_j= 25^{\circ}\text{C}$ , $I_{FM}=0.5\text{A}$	-	-	0.45	V
Thermal Resistance	$R_{th(j-a)}$	Junction to Ambient *	-	-	300	$^{\circ}\text{C}/\text{W}$
	$R_{th(j-l)}$	Junction to Lead	-	-	70	

\*1: Glass Epoxy Substrate Mounted (Soldering Lands=1x1mm,Both Sides)  
( $T_l$ : Lead Temperature)

EP05Q03L OUTLINE DRAWING (Dimensions in mm)

